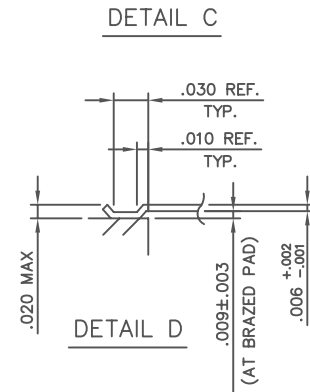
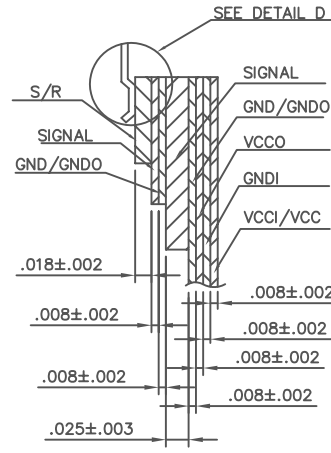
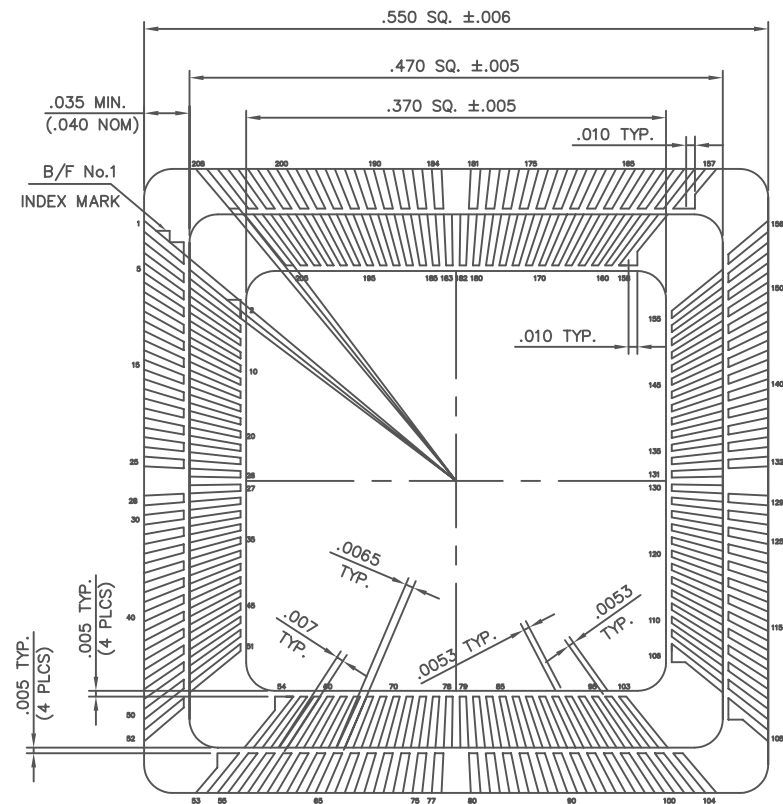




# SSM P/N CCF10007



REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVAL

## WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

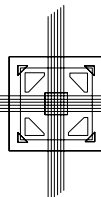
W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	GNDO	53	VCCO	105	GNDO	157	VCCO
2	VCC	54	GNDO	106	VCC	158	GNDO
3	55	55	27	107	52	159	77
4	GNDO	56	GNDO	108	GNDO	160	GNDO
5	GNDO	57	GNDO	109	GNDO	161	GNDO
6	3	58	28	110	53	162	78
7	VCCO	59	VCCO	111	VCCO	163	VCCO
8	VCCO	60	VCCO	112	VCCO	164	VCCO
9	4	61	29	113	54	165	79
10	GNDO	62	GNDO	114	GNDO	166	GNDO
11	GNDO	63	GNDO	115	GNDO	167	GNDO
12	5	64	30	116	55	168	80
13	VCC	65	VCC	117	VCC	169	VCC
14	6	66	31	118	56	170	81
15	GNDO	67	GNDO	119	GNDO	171	GNDO
16	7	68	32	120	57	172	82
17	GNDI	69	GNDI	121	GNDI	173	GNDI
18	8	70	33	122	58	174	83
19	VCCI	71	VCCI	123	VCCI	175	VCCI
20	10	72	35	124	60	176	85
21	VCCO	73	VCC	125	VCCO	177	VCC
22	11	74	36	126	61	178	86
23	GNDO	75	GNDO	127	GNDO	179	GNDO
24	12	76	37	128	62	180	87
25	VCCO	77	VCCO	129	VCCO	181	VCCO
26	13	78	38	130	63	182	88
27	GNDO	79	GNDO	131	GNDO	183	GNDO
28	GNDO	80	GNDO	132	GNDO	184	GNDO
29	14	81	39	133	64	185	89
30	GND	82	GND	134	GND	186	GND
31	15	83	40	135	65	187	90
32	VCCO	84	VCC	136	VCCO	188	VCC
33	16	85	41	137	66	189	91
34	GNDO	86	GNDO	138	GNDO	190	GNDO
35	18	87	43	139	68	191	93
36	GNDO	88	GNDO	140	GNDO	192	GNDO
37	19	89	44	141	69	193	94
38	VCCI	90	VCCI	142	VCCI	194	VCCI
39	20	91	45	143	70	195	95
40	GNDI	92	GNDI	144	GNDI	196	GNDI
41	21	93	46	145	71	197	96
42	GND	94	GND	146	GND	198	GND
43	GND	95	GND	147	GND	199	GND
44	22	96	47	148	72	200	97
45	VCCO	97	VCCO	149	VCCO	201	VCCO
46	VCCO	98	VCCO	150	VCCO	202	VCCO
47	23	99	48	151	73	203	98
48	GNDO	100	GNDO	152	GNDO	204	GNDO
49	GNDO	101	GNDO	153	GNDO	205	GNDO
50	24	102	49	154	74	206	99
51	VCC	103	GNDO	155	VCC	207	GNDO
52	GNDO	104	VCCO	156	GNDO	208	VCCO

GND/GNDO : LEAD No. 1,25,34,51,75,84,92  
 VCCO : LEAD No. 9,42,100  
 GNDI : LEAD No. 26,50,59  
 VCCI/VCC : LEAD No. 17,67,76

### NOTES:

- PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
- SEAL AREA TO BE METALLIZED.
- SEAL RINGS TO BE FLOATING FROM ANY PINS.
- DIE ATTACH AREA TO BE METALLIZED.
- DIE ATTACH AREA TO BE FLOATING FROM ANY PINS.
- LEAD RESISTANCE: (AT THE CLOSEST BRAZE PAD)  
 SIGNAL ----- 500 m OHMS MAX.  
 POWER/GROUND ----- 300 m OHMS MAX.
- LEAD CAPACITANCE: SIGNAL ----- IT.B.DI
- LEAD INDUCTANCE: SIGNAL ----- IT.B.DI  
 POWER/GROUND ----- IT.B.DI
- INSULATION RESISTANCE: SIGNAL --- 10uA AT 100V.  
 POWER/GROUND ----- 100uA AT 100V.
- REFERENCE KYOCERA DWG # KD-F98406-C.

Controlling Units millimeters <input type="checkbox"/> inches <input checked="" type="checkbox"/> .X=±.1 .XX=±.02 .XXX=±.005 .XXXX=±.0002 Angles=±2°	PJ Drawn	7-31-98	Date						
	Check		Date						
	Approved		Date						
	Approved		Date						
F010029.B	Code Ident		2M	Size	B	Drawing No.	6300626	Rev	A
Scale		CAD File No.		0626PKA		Sheet 2 of 2			



**SPECTRUM**  
 SEMICONDUCTOR MATERIALS, INC.

www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226